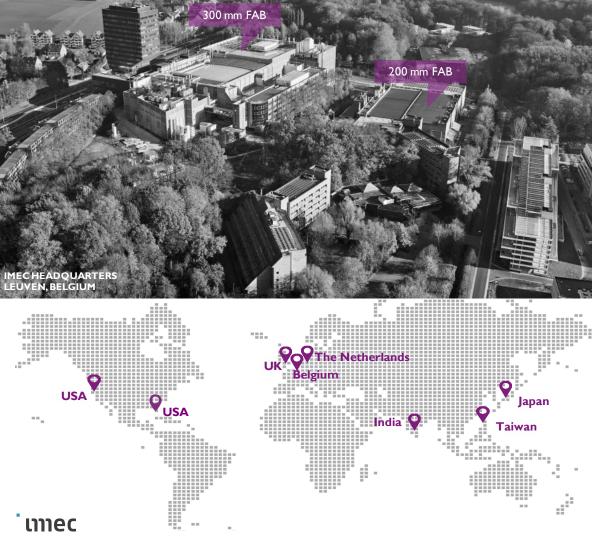
Inec

Extending the CMOS technology roadmap with system technology co-optimization James Myers STCO Program Director & UK Site Manager

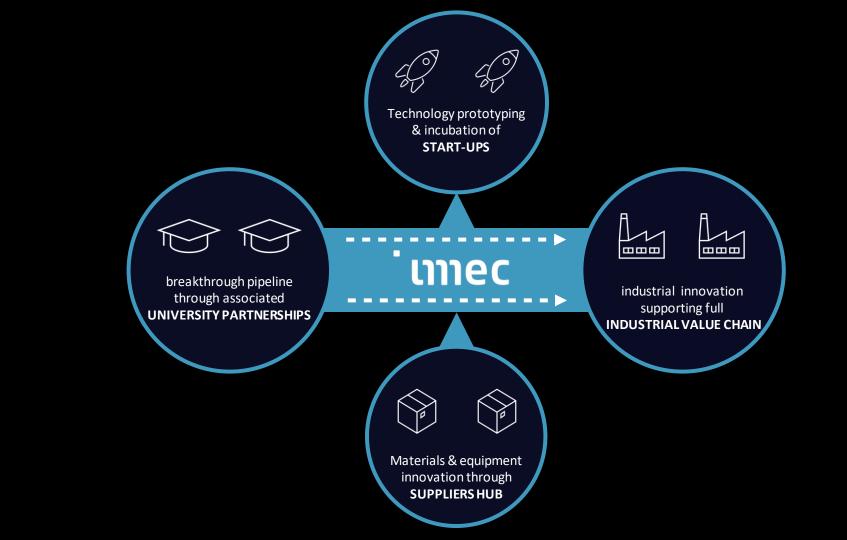


- An introduction to imec and imec UK
- The CMOS technology landscape through system eyes
- System Technology Co-optimization (STCO): what system, what technology?
- How does STCO work and what does it get us?



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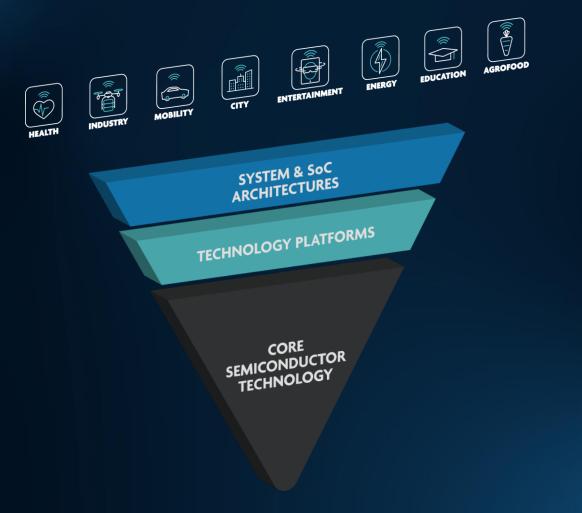
- World-leading R&D in nanoelectronics & digital technology
- Delivering industry relevant
 technology R&D solutions for ICT,
 Healthcare and Energy markets 5-10
 years ahead of market introduction
- 5500 international R&D top talents from 95 nationalities
- Unique € 3.5B leading edge semiconductor R&D fabs
- € 845M revenues: 75% industry, 16% regional gov't, 9 % EU & regional programs
- Not-for-profit R&D center
- Created 120+ spin-off companies since 1984



BUSINESS MODELS TO CREATE IMPACT







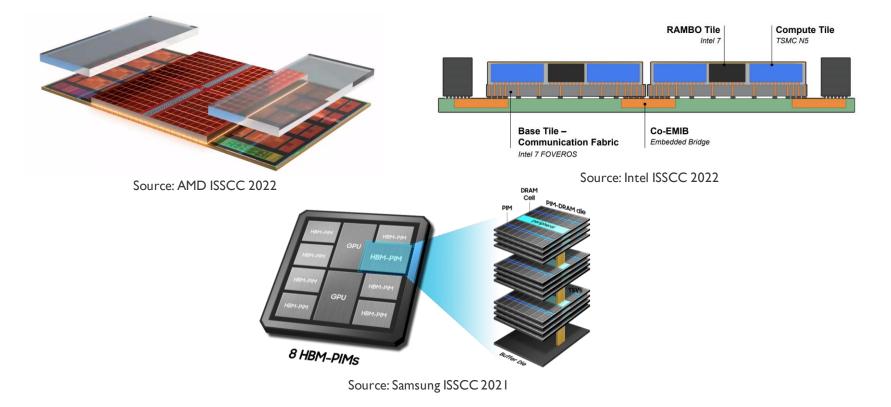


- Founded August 2022 to access UK design expertise
- Currently a team of 9 circuit and system researchers with experience of cross stack projects from device through circuits and system to algorithms
- Active projects in optical & wireless comms, novel memory, computer architecture
- Now collaborating with UK academia through co-funded & co-supervised PhDs
- Keen to discuss other UK collaboration models
- We're hiring!
 - https://www.imec-int.com/en/work-at-imec/job-opportunities



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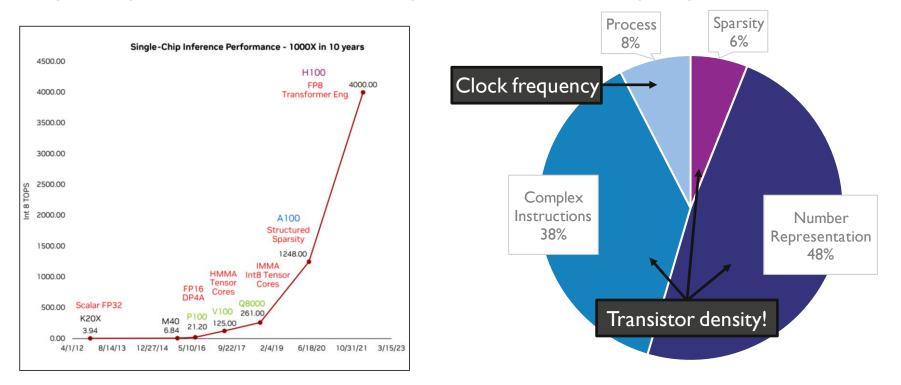
Many innovations hitting today's SoC products



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Transistor density = specialism = performance

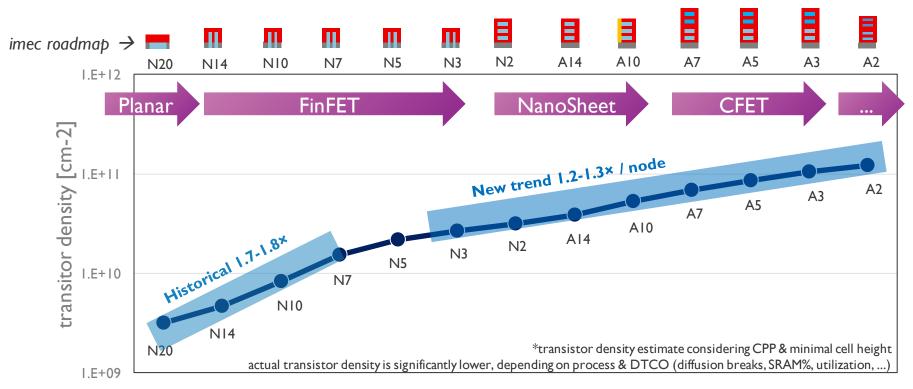
Density scaling enables architects to boost performance at iso-frequency



[Bill Dally, Nvidia, Hot Chips 2023]

But transistor density scaling projected to slow down

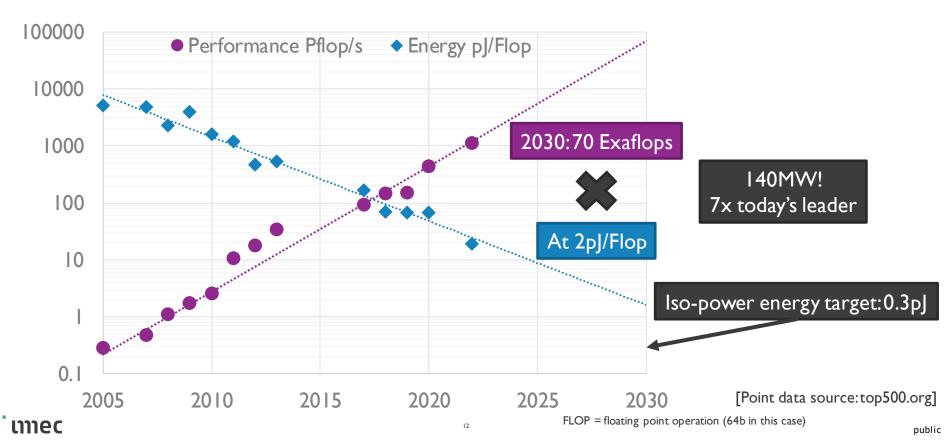
CPP x cell height scaling stalling



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The world's fastest supercomputers 2005-2030

Efficiency falling behind continued performance improvements



We have an open benchmarking issue

Imec can fill this gap – N2 P-PDK and beyond

		Relative Energy Cost				
Operation:	Energy (pJ)					
8b Add	0.03]				
16b Add	0.05					
32b Add	0.1					
16b FP Add	0.4					
32b FP Add	0.9					
8b Mult	0.2					
32b Mult	3.1					
16b FP Mult	1.1					
32b FP Mult	3.7					
32b SRAM Read (8KB)	5					
32b DRAM Read	640					

**Energy numbers from 45nm process

[Bill Dally, Nvidia, Hot Chips 2023]

		Picojoules per Operation					Ratio	
Operation		N45		N7		N2 (imec)		N2/N7
	IEEE FP32		0.9		0.38		0.346	91%
	IEEE FP16	Ι,	0.4		0.16	<u> </u>	0.187	117%
	BFloat16		30×		0.11	100>	0.146	133%
	Int32	╵╹	0.1		0.03		0.019	63%
Add	Int8		0.03		0.007		0.003	45%
	IEEE FP32		3.7		1.31		0.734	56%
	IEEE FP16		1.1		0.34		0.215	63%
	BFloat16		20x		0.21	30x	0.096	46%
	Int32	L	3.1		1.48		0.562	38%
Multiply	Int8		0.2		0.07		0.023	33%

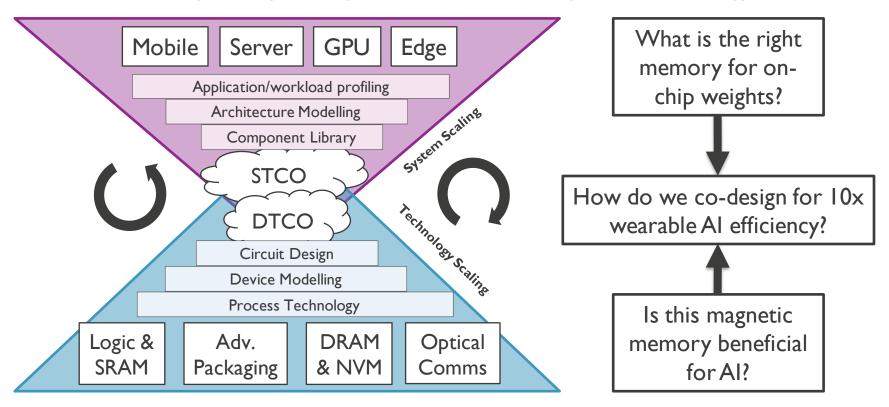
[imec paper under review]



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Imec's STCO vision

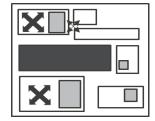
The future of compute depends upon cross-stack codesign with technology innovations



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Divergent SoC directions

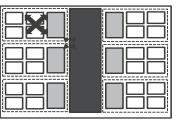
Mobile



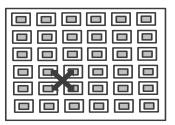
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X

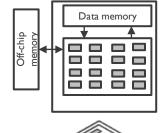
Cloud Server

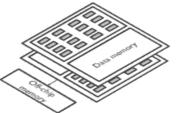


Datacenter GPU



XR Wearables







X

Arch

Package



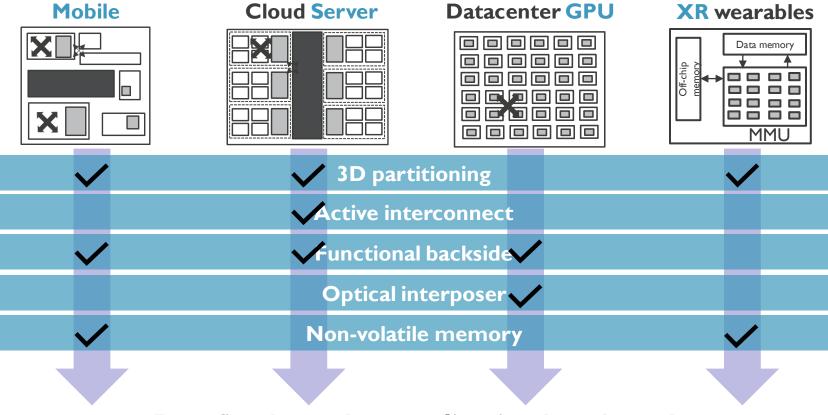






umec

Technology choices are application dependent



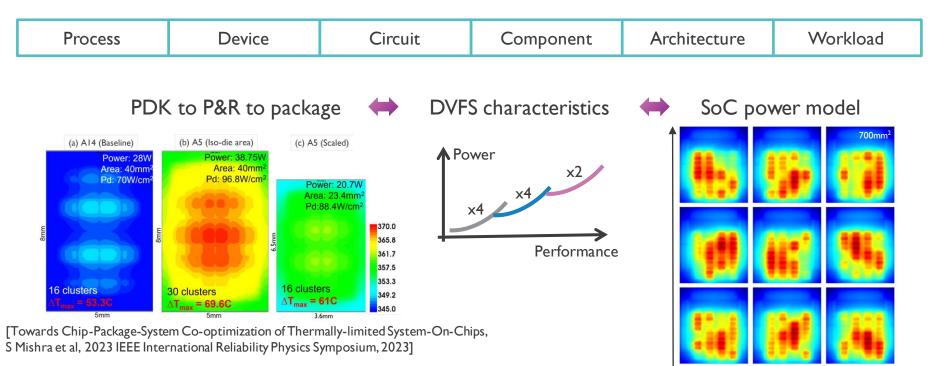
Benefits depend on application benchmark



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How much does thermal management limit future performance?

Output: thermally aware CMOS roadmap enhanced for performance at fixed TDP

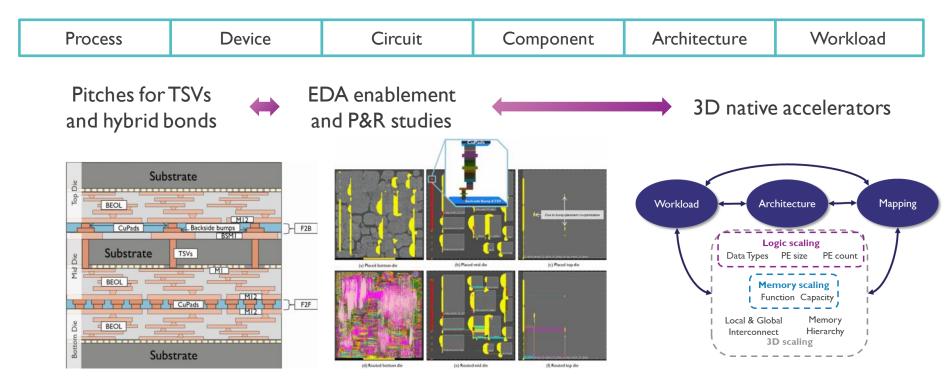


Workload mappings

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How can we get the most from 3D SoCs?

Output: aligned usage model for 3D pitch, CMOS and embedded memory roadmaps



[M. Naeim et al., "Design Enablement of 3-Dies Stacked 3D-ICs Using Fine-Pitch Hybrid-Bonding and TSVs," 2023 IEEE International 3D Systems Integration Conference]

ເກາec



- Imec is a semiconductor technology institute with growing presence in the UK
- CMOS logic density scaling continues but we have many system problems to tackle
- Imec's STCO research enriches future technology roadmaps with system context
- We will increasingly rely on STCO to extend Moore's Law
 - And need more UK designers to get involved in technology research

embracing a better life